

Product Change Notification - JAON-15BYTH145

Date: 05 Jul 2017
Product Category: KEELOQ® Encoder Devices; KEELOQ® Decoder Devices; 8-bit PIC Microcontrollers
Notification subject: CCB 2597 Final Notice: Qualification of CuPdAu bond wire in selected products of the 90K and 120K wafer technologies available in 8L SOIJ package at MTAI assembly site.
Notification text: **PCN Status:**
 Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 90K and 120K wafer technologies available in 8L SOIJ package at MTAI assembly site.

Pre Change:

Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8390A	8390A
Molding compound material	G600	G600
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 28, 2017 (date code: 1730)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2016					->	July 2017			
Workweek	22	23	24	25	26		27	28	29	30
Initial PCN Issue Date			X							
Qual Report Availability							X			
Final PCN Issue Date							X			
Estimated Implementation Date										X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

June 13, 2016: Issued initial notification.

July 5, 2017: Issued final notification. Attached the qualification report. Provided estimated first ship date on July 28, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-15BYTH145_Qual Report.pdf](#)

[PCN_JAON-15BYTH145_Affected CPN.pdf](#)

[PCN_JAON-15BYTH145_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15BYTH145
CATALOG_PART_NBR
HCS365/SM
HCS365-I/SM
HCS365T/SM
HCS365T-I/SM
HCS500/SM
HCS500-I/SM
HCS500T/SM
PIC12C508-04/SM
PIC12C508-04E/SM
PIC12C508-04I/SM
PIC12C508A-04/SM
PIC12C508A-04E/SM
PIC12C508A-04I/SM
PIC12C508AT-04/SM
PIC12C508AT-04/SM048
PIC12C508AT-04/SM096
PIC12C508AT-04/SM139
PIC12C508AT-04/SM232
PIC12C508AT-04/SM233
PIC12C508AT-04E/SM
PIC12C508AT-04I/SM
PIC12C508AT-04I/SM112
PIC12C508AT-04I/SM142
PIC12C508AT-04I/SM194
PIC12C508AT-04I/SM226
PIC12C508AT-04I/SM236
PIC12C508T-04/SM
PIC12C508T-04/SM038
PIC12C508T-04I/SM
PIC12C509-04/SM
PIC12C509-04E/SM
PIC12C509-04I/SM
PIC12C509A-04/SM
PIC12C509A-04E/SM
PIC12C509A-04I/SM
PIC12C509AT-04/SM
PIC12C509AT-04/SM022
PIC12C509AT-04/SM091
PIC12C509AT-04E/SM
PIC12C509AT-04I/SM
PIC12C509AT-04I/SM135
PIC12C509T-04/SM
PIC12C509T-04E/SM

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15BYTH145
CATALOG_PART_NBR
PIC12C509T-04I/SM
PIC12C509T-04I/SM030
PIC12C671-04/SM
PIC12C671-04/SMC01
PIC12C671-04E/SM
PIC12C671-04I/SM
PIC12C671-04I/SM050
PIC12C671-10/SM
PIC12C671-10I/SM
PIC12C671T-04/SM
PIC12C671T-04/SM067
PIC12C671T-04/SMC01
PIC12C671T-04E/SM
PIC12C671T-04I/SM
PIC12C671T-04I/SM040
PIC12C671T-04I/SM066
PIC12C671T-10I/SM
PIC12C671T-10I/SM070
PIC12C672-04/SM
PIC12C672-04E/SM
PIC12C672-04I/SM
PIC12C672-10/SM
PIC12C672-10E/SM
PIC12C672-10I/SM
PIC12C672T-04/SM
PIC12C672T-04I/SM
PIC12C672T-04I/SM028
PIC12CR509AT-04I/SM021
PIC12LC508A-04/SM
PIC12LC508A-04I/SM
PIC12LC508AT-04/SM
PIC12LC508AT-04/SMC01
PIC12LC508AT-04I/SM172
PIC12LC509A-04/SM
PIC12LC509A-04I/SM
PIC12LC509AT-04I/SM
PIC12LC671-04/SM
PIC12LC671-04I/SM
PIC12LC672-04/SM
PIC12LC672-04I/SM